



C5 C6 can be not installed if Vin is higher than 0.5Vac(peak)

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Orderable: N/A	Designed for: Public Release	Mod. Date: 11/19/2015
TID #: PMP9777	Project Title: Getting Power from Earphone Jack	
Number: PMP9777	Rev: E1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: [No Variations]	Sheet: 2 of 3
Drawn By:	File: BlankSheet_SchDoc	Size: B
Engineer: Charles Wong	Contact: http://www.ti.com/support	

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